[19] Patents Registry
The Hong Kong Special Administrative Region
香港特別行政區
專利註冊處

[11] 1026334 A

[12] **SHORT-TERM PATENT SPECIFICATION**

短期專利說明書

[21] Application No. 申請編號
99102892.7

[22] Date of filing 提交日期
07.07.1999

[51] Int.Cl.[7] C09J H01L

[30] Priority 優先權
07.07.1998 KR 98-27292

[45] Publication Date of granted patent 批予專利的發表日期
10.11.2000

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[54] ADHESIVE COMPOSITION FOR BONDING SEMICONDUCTOR CHIPS 用以粘合半導體片的粘附性化合物

[57] Disclosed is an adhesive resin composition for bonding semiconductor chips comprising an adhesive resin component, a curing agent, a diluent, a curing promoter, a thixotropic agent, and an inorganic filler component. The resin component is approximately 10-50% by weight, and the inorganic filler component is approximately 50-90% by weight and comprises a copper ingredient and a silver ingredient. The copper ingredient is selected from the group consisting of CuO, Cu_2O, with the mixtures thereof being approximately 0.1-50% by weight based on the total weight of said inorganic filler component. The silver ingredient is approximately 50-99.0% by weight based on the total weight of the inorganic filler ingredient.
本說明介紹的是一種用以粘合半導體片的粘附性樹脂化合物。它由一粘附性樹脂成分、一固化劑、一固化促進劑、一觸變劑及一無機填物成分組成。樹脂成分約佔化合物重量的 10-50%，而無機填物則約佔化合物重量的 50-90%，並包含一銅成分與一銀成分。銅成分選自 CuO 與 Cu_2O 組。含銅混合物佔無機填物總重量的 0.1-50%，含銀混合物約佔無機填物總重量的 50-99.0%。